L Number	Hits	Search Text	DB	Time stamp
-	1571	204/$.ccls. and (wafer or semiconductor) and seal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/20 08:59
-	531	(204/198,232,237,242,275.1,297.01,297.06,297.14.ccls. 204/224r,224m.ccls.) and (wafer or semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 08:46
-	218	((204/198,232,237,242,275.1,297.01,297.06,297.14.ccls 204/224r,224m.ccls.) and (wafer or semiconductor)) and seal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 10:30
-	60	(204/198,232,237,242,275.1,297.01,297.06,297.14.ccls. 204/224r,224m.ccls.) and sponge	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 09:18
-	2	6176992.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 09:25
-	14	("3595089" | "4610772" | "5024735" | "5171412" | "5429733" | "5558568" | "5692947" | "5755859" | "5807165" | "5833820" | "5863412" | "5930669" | "5933753" | "6004880").PN.	USPAT	2003/10/27 09:26
-	2	6228233.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 09:33
-	2	4807973.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 09:33
-	23	(204/$.ccls. or 205/$.ccls.) and datta.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 10:33
-	3838	204/198,232,237,242,275.1,297.01,297.06,297.14.ccls. 204/224r,224m.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 10:53

-	313	(204/198,232,237,242,275.1,297.01,297.06,297.14.ccls. 204/224r,224m.ccls.) and (temperature with (anode or cathode or electrode))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 10:54
-	67	(204/198,232,237,242,275.1,297.01,297.06,297.14.ccls. 204/224r,224m.ccls.) and (temperature near2 (anode or cathode or electrode))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 11:03
-	10	3859196.URPN.	USPAT	2003/10/27 11:01
-	30	(204/198,232,237,242,275.1,297.01,297.06,297.14.ccls. 204/224r,224m.ccls.) and ((temperature near2 control$5) with (anode or cathode or electrode))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 11:13
-	2	("5507923" | "6017437").PN.	USPAT	2003/10/27 11:06
-	25	(204/198,232,237,242,275.1,297.01,297.06,297.14.ccls. 204/224r,224m.ccls.) and ((coolant or (cooling adj (fluid or liquid))) with (anode or cathode or electrode))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 11:19
-	531	(204/198,232,237,242,275.1,297.01,297.06,297.14.ccls. 204/224r,224m.ccls.) and (wafer or semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 11:20
-	375	((204/198,232,237,242,275.1,297.01,297.06,297.14.ccls 204/224r,224m.ccls.) and (wafer or semiconductor)) and (coolant or (cooling fluid) or heat or heating)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 11:22
-	176	((204/198,232,237,242,275.1,297.01,297.06,297.14.ccls 204/224r,224m.ccls.) and (wafer or semiconductor)) and ((coolant or (cooling fluid) or heat or heating) with (anode or cahode or electrode))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 11:22
-	93	((204/198,232,237,242,275.1,297.01,297.06,297.14.ccls 204/224r,224m.ccls.) and (wafer or semiconductor)) and ((coolant or (cooling fluid) or heat or heating) near3 (anode or cahode or electrode))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 11:21
-	9	((204/198,232,237,242,275.1,297.01,297.06,297.14.ccls 204/224r,224m.ccls.) and (wafer or semiconductor)) and ((coolant or (cooling adj fluid) or heat or heating) near3 (anode or cahode or electrode))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 11:21
-	197	((204/198,232,237,242,275.1,297.01,297.06,297.14.ccls 204/224r,224m.ccls.) and (wafer or semiconductor)) and (coolant or (cooling adj fluid) or heat or heating)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 11:22

-	32	((204/198,232,237,242,275.1,297.01,297.06,297.14.ccls 204/224r,224m.ccls.) and (wafer or semiconductor)) and ((coolant or (cooling adj fluid) or heat or heating) with (anode or cahode or electrode))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 11:22
-	2	("5507923" | "6017437").PN.	USPAT	2003/10/27 11:27
-	0	868577.apn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 11:42
-	22	(US-6077412-$ or US-6017437-$ or US-5951833-$ or US-5567300-$ or US-5776330-$ or US-6176992-$ or US-6228233-$ or US-6251235-$ or US-6258240-$ or US-6261433-$ or US-6270647-$ or US-6328872-$ or US-6334937-$ or US-6103096-$ or US-5284554-$ or US-3859196-$ or US-6398926-$ or US-5228966-$ or US-5198083-$ or US-3894925-$ or US-3637468-$).did. or (US-20020056647-$).did.	USPAT; US-PGPUB	2003/10/27 11:50
-	8	((US-6077412-$ or US-6017437-$ or US-5951833-$ or US-5567300-$ or US-5776330-$ or US-6176992-$ or US-6228233-$ or US-6251235-$ or US-6258240-$ or US-6261433-$ or US-6270647-$ or US-6328872-$ or US-6334937-$ or US-6103096-$ or US-5284554-$ or US-3859196-$ or US-6398926-$ or US-5228966-$ or US-5198083-$ or US-3894925-$ or US-3637468-$).did. or (US-20020056647-$).did.) and ((electrolyte or solution or fluid) with (temperature or cool$4 or heat$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 11:51
-	7	((US-6077412-$ or US-6017437-$ or US-5951833-$ or US-5567300-$ or US-5776330-$ or US-6176992-$ or US-6228233-$ or US-6251235-$ or US-6258240-$ or US-6261433-$ or US-6270647-$ or US-6328872-$ or US-6334937-$ or US-6103096-$ or US-5284554-$ or US-3859196-$ or US-6398926-$ or US-5228966-$ or US-5198083-$ or US-3894925-$ or US-3637468-$).did. or (US-20020056647-$).did.) and (dc or (direct adj current))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 12:32
-	0	868577.apn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/20 08:59
-	2655	204/198,232,237,242,275.1,297.01,297.06,297.14.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/20 09:50

-	68	204/198,232,237,242,275.1,297.01,297.06,297.14.ccls. and (ammeter or (current near (detect$4 or sensor or sense or sensing or sensed)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/20 10:01
-	1521	204/224r,224m.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/20 10:01
-	47	204/224r,224m.ccls. and (ammeter or (current near (detect$4 or sensor or sense or sensing or sensed)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/20 10:16
-	42	(204/224r,224m.ccls. and (ammeter or (current near (detect$4 or sensor or sense or sensing or sensed)))) not (204/198,232,237,242,275.1,297.01,297.06,297.14.ccls. and (ammeter or (current near (detect$4 or sensor or sense or sensing or sensed))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/20 10:03
-	1686	205/118,122,125.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/20 10:04
-	17	205/118,122,125.ccls. and (ammeter or (current near (detect$4 or sensor or sense or sensing or sensed)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/20 10:04
-	0	868577.apn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/12 10:49
-	614	204/229.8.ccls. 205/775,790.5,791.5.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/12 10:49
-	5	(204/229.8.ccls. 205/775,790.5,791.5.ccls.) and (pinhole or (pin adj hole))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/12 11:01
-	18	4473795.URPN.	USPAT	2004/08/12 10:52
-	64	(204/229.8.ccls. 205/775,790.5,791.5.ccls.) and (cavity or discontinuity)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/12 11:02

-	94	(204/229.8.ccls. 205/775,790.5,791.5.ccls.) and (cavity or discontinuity or defect)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/12 11:02
-	12	(204/229.8.ccls. 205/775,790.5,791.5.ccls.) and ((cavity or discontinuity or defect) with current)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/12 11:03
-	4	("3373353" | "3772520" | "3792458" | "4296372").PN.	USPAT	2004/08/12 11:25
-	10	3792458.URPN.	USPAT	2004/08/12 11:26